

MLC NAND FLASH

Family	Density	Technology	Part Number	Package Type	Org.	Vol(V)	MOQ		Remarks
							Tray	T/R	
							-xxxx0xx	-xxx0Txx	
16Gb based 4KByte/Page Cache	128Gb DSP	51nm	K9MDG08U5M-PCB0	TSOP1	x8	3.3	960	1,000	
			K9MDG08U5M-ZCB0	WELP	x8	3.3	960	1,000	
	64Gb QDP		K9HCG08U1M-PCB0	TSOP1	x8	3.3	960	1,000	
			K9HCG08U1M-IIB0	ULGA	x8	3.3	960	1,000	
	32Gb DDP		K9LBG08U0M-PCB0	TSOP1	x8	3.3	960	1,000	
			K9LBG08U1M-IIB0	ULGA	x8	3.3	720	2,000	2CE
	16Gb mono		K9GAG08U0M-PCB0	TSOP1	x8	3.3	960	1,000	
			K9GAG08U0M-IIB0	ULGA	x8	3.3	720	2,000	
8Gb Based 2KByte/Page W/O Cache	32Gb QDP	59nm	K9HBG08U1B-PCB0	TSOP1	x8	3.3	960	1,000	
	16Gb DDP	51nm	K9LAG08U0A-PCB0	TSOP1	x8	3.3	960	1,000	qualify B-die part # K9LAG08U0B-PCB0000
		59nm	K9LAG08U0B-PCB0	TSOP1	x8	3.3	960	1,000	
	8Gb mono	51nm	K9G8G08U0A-PCB0	TSOP1	x8	3.3	960	1,000	qualify B-die, part # K9G8G08U0B-PCB0000
			K9G8G08U0A-IIB0	ULGA	x8	3.3	960	2,000	
		59nm	K9G8G08U0B-PCB0	TSOP1	x8	3.3	960	1,000	
4Gb based	4Gb mono	63nm	K9G4G08U0A-PCB0	TSOP1	x8	3.3	960	1,000	qualify B-die, part # K9G4G08U0B-PCB0000
		51nm	K9G4G08U0B-PCB0	TSOP1	x8	3.3	960	1,000	

Please contact your local Samsung sales representative for latest product offerings.

Note: All parts are lead free